Dual N-Channel 40 V (D-S) Super Junction MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (mΩ) (Typ.)	I_D (A)[a]	Q_g (Typ.)
40	6.6 at V_{GS} = 10 V	48	13 nC
	9.7 at V_{GS} = 4.5 V		

FEATURES

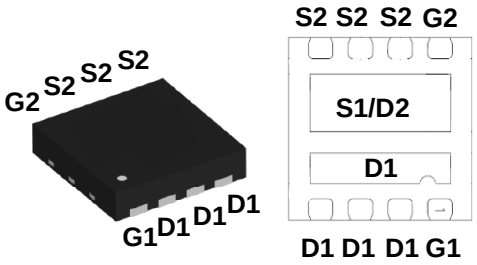
- DT-SJ Power MOSFET
- 100 % R_g and UIS tested
- Integrated MOSFET half-bridge power stage

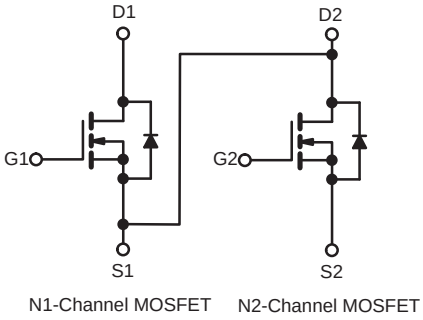
RoHS COMPLIANT

APPLICATIONS

- Synchronous Rectification
- Motor Drives and Uninterruptible Power Supplies

DFN3x3 Asymmetric Dual Pin Configuration





ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	48	A
	T_C = 100 °C		32	
Pulsed Drain Current		I_{DM}	160	
Single Avalanche Energy [a]	L = 0.1 mH	E_{AS}	50	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	30[b,c]	W
	T_C = 100 °C		21.2[b,c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150	°C
Soldering Recommendations (Peak Temperature)			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount)[b,d]	t ≤ 10 s	R_{thJA}	30	°C/W
Junction-to-Case (Drain)	Steady State	R_{thJC}	4.2	

Notes:
a. T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under steady state conditions is 40 °C/W.

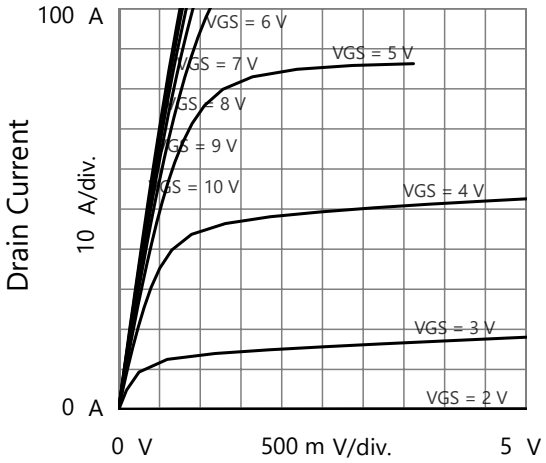
SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	40	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1	-	2.5	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 40 V, V_{GS} = 0 V	-	-	1	µA
		V_{DS} = 32 V, V_{GS} = 0 V, T_J = 55 °C	-	-	10	
On-State Drain Current [a]	$I_{D(on)}$	V_{DS} ≥ 10 V, V_{GS} = 10 V	48	-	-	A
Drain-Source On-State Resistance [a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 10 A	-	6.6	9	mΩ
		V_{GS} = 4.5 V, I_D = 7 A	-	9.7	15	
Forward Transconductance [a]	g_{fs}	V_{DS} = 5 V, I_D = 10 A	-	40	-	S
Dynamic [b]						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 20 V, f = 1 MHz	-	712	-	pF
Output Capacitance	C_{oss}		-	423	-	
Reverse Transfer Capacitance	C_{rss}		-	26	-	
Total Gate Charge [c]	Q_g	V_{DS} = 20 V, V_{GS} = 10 V, I_D = 10 A	-	13	-	nC
Gate-Source Charge [c]	Q_{gs}		-	1.3	-	
Gate-Drain Charge [c]	Q_{gd}		-	2.4	-	
Gate Resistance	R_g	f = 1 MHz	-	6	-	Ω
Turn-On Delay Time [c]	$t_{d(on)}$	V_{DS} = 20 V, I_D = 10 A, R_g = 2.5 Ω V_{GS} = 10 V	-	10	-	ns
Rise Time [c]	t_r		-	9	-	
Turn-Off Delay Time [c]	$t_{d(off)}$		-	52	-	
Fall Time [c]	t_f		-	27	-	
Drain-Source Body Diode Ratings and Characteristics [b] (T_C = 25 °C)						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C	-	-	48	A
Pulsed Current (t = 100 µs)	I_{SM}		-	-	160	A
Forward Voltage [a]	V_{SD}	I_F = 100 A, V_{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t_{rr}	I_F = 10 A, di/dt = 300 A/µs	-	19	-	ns
Reverse Recovery Charge	Q_{rr}		-	10	-	nC

Notes

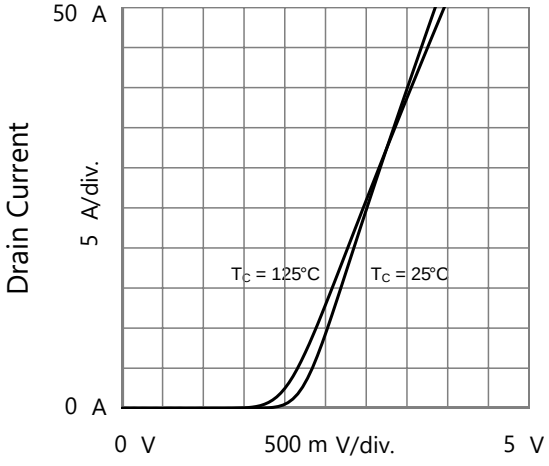
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

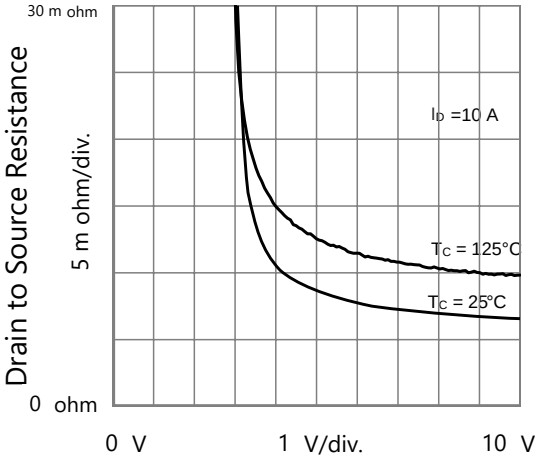
TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)



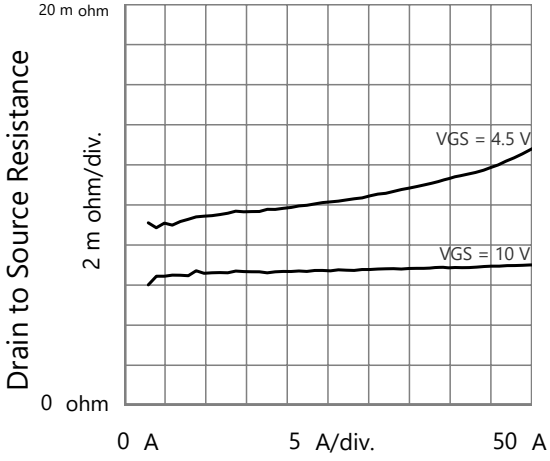
Drain to Source Voltage
Output Characteristics



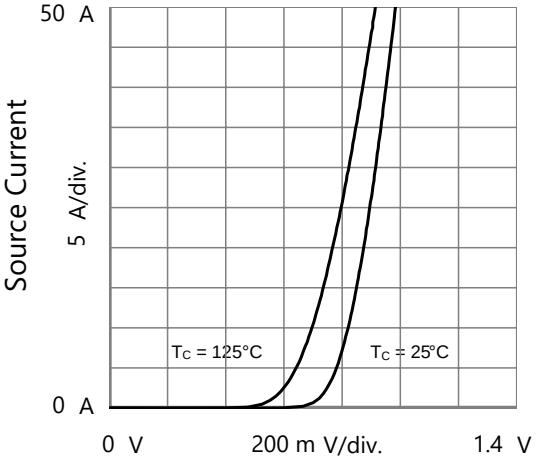
Gate to Source Voltage
Transfer Characteristics



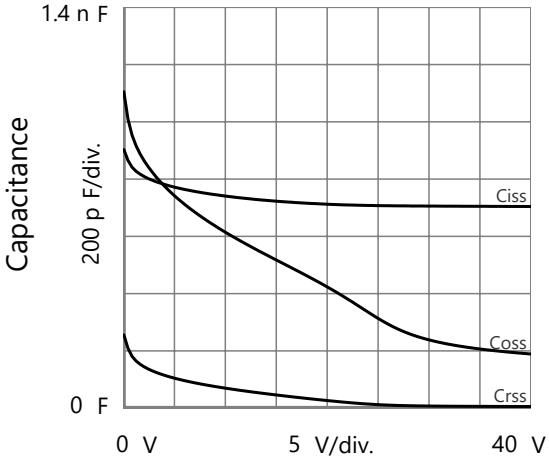
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



Drain Current
Drain to Source Resistance vs. Drain Current

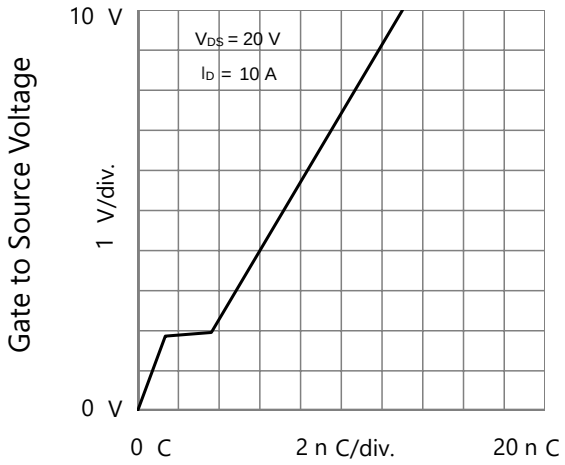


Source to Drain Voltage
Body Diode Forward Characteristics

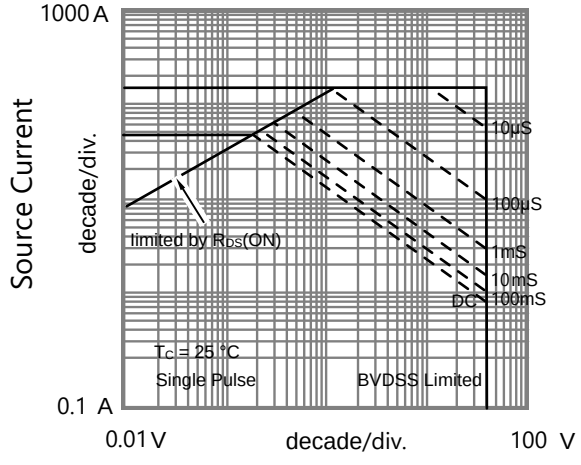


Drain to Source Voltage
Capacitances

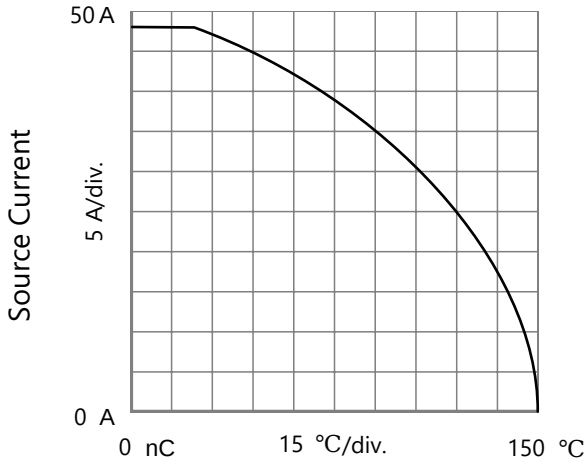
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

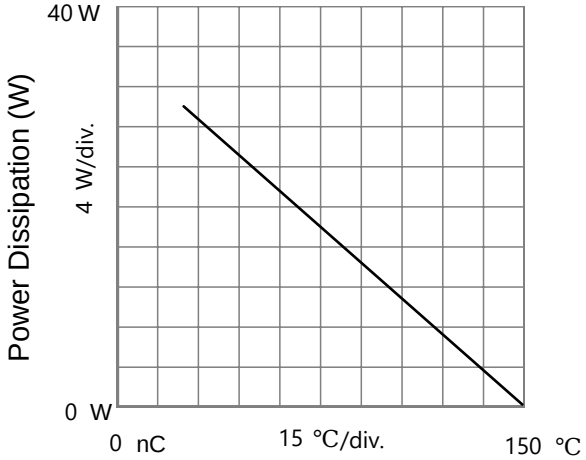


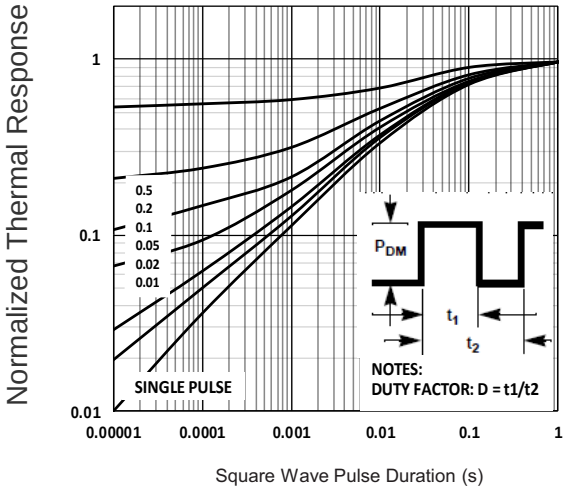
Gate to Source Voltage vs. GateCharge



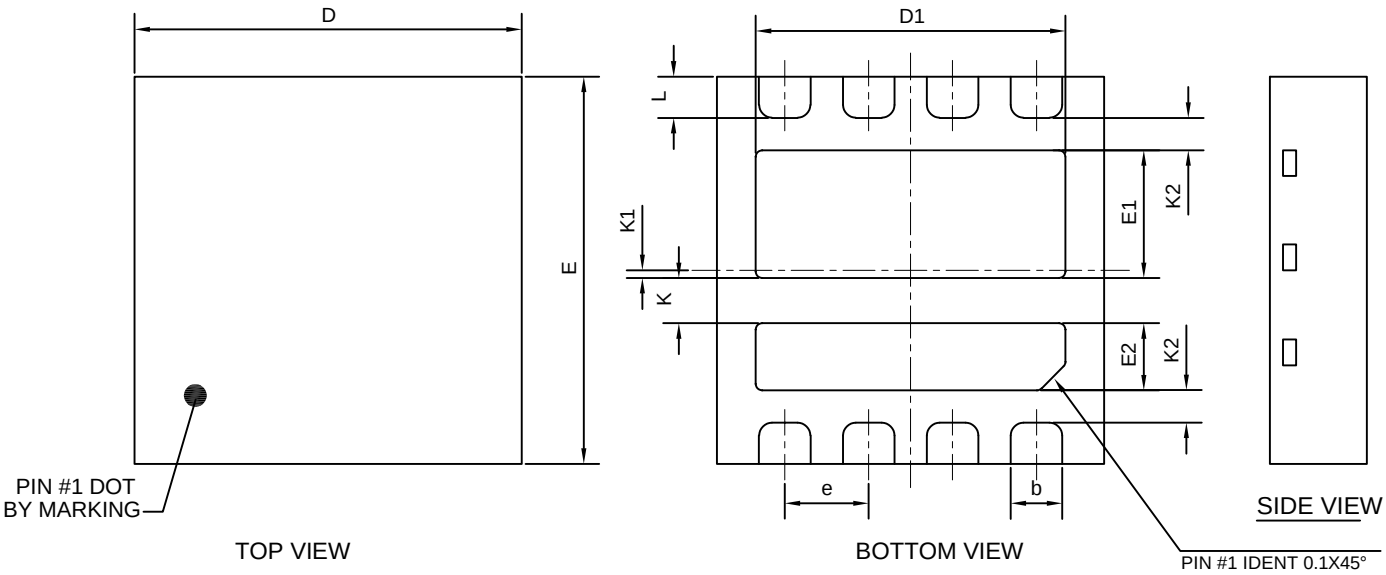
Safe Operating Area, Junction-to-Ambient

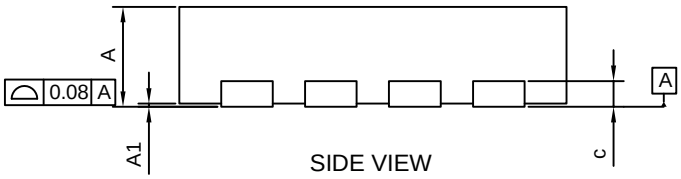


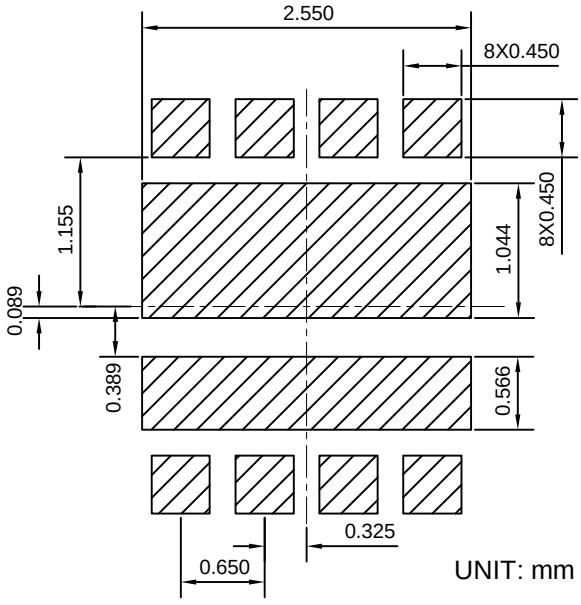




DFN3X3-8L-D PACKAGE OUTLINE







RECOMMENDED LAND PATTERN

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	-	0.05
c		0.203 REF.	
b	0.35	0.40	0.45
D	2.90	3.00	3.10
D1	2.30	2.40	2.50
E	2.90	3.00	3.10
E1	0.89	0.99	1.09
E2	0.42	0.52	0.62
e		0.65 BSC	
L	0.27	0.32	0.37
K		0.35 REF.	
K1		0.06 REF.	
K2		0.25 REF.	

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